

METHOD OF APPLICATION OF CONDUCTIVE CAP-LAYER IN FLIP-CHIP, COB, AND MICRO METAL BONDING

ABSTRACT

A method of bonding a bonding element to a metal bonding pad comprises the following steps. A semiconductor structure having an exposed, recessed metal bonding pad within a layer opening is provided. The layer has an upper surface. A conductive cap having a predetermined thickness is formed over the metal bonding pad. A bonding element is bonded to the conductive cap to form an electrical connection with the metal bonding pad.

Fig. 8